Allwinner H8 Datasheet

Revision 1.1

Nov.20, 2014

REVISION HISTORY

Version	Date	Description
1.0	Sep.20, 2014	Initial Release Version
1.1	Nov.20,2014	Change the Feature of Video Engine

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1. OVERVIEW

The Allwinner's H8 is a remarkably lower power, high performance octa-core home entertainment processor based on ARM Cortex^{TM}-A7 CPU along with SGX544MP1 GPU architecture. It is also highly competitive in term of system cost   thanks to its high system integration and is capable of delivering excellent user experience while maintaining low power consumption.

Main features of H8 include:
• CPU architecture: Based on an octa-core Cortex^{TM}-A7 CPU architecture, the most power efficient CPU core ARM's ever developed.
• Graphics: H8 adopts the extensively implemented and technically mature PowerVR SGX544MP1 to provide mobile users with superior experience in web browsing, video playback and games; OpenGL ES1.1/2.0 , OpenCL1.1 and DirectX 9.3 standards are supported.
• Video Engine: Multi-format playback of up to 4K high-definition video, and support MPEG1/2, MPEG4 SP/ASP GMC, H.263 including Sorenson Spark, H.264 BP/MP/HP, VP8, WMV9/VC1, JPEG/MJPEG standards with dedicated hardware, and HEVC/H.265 decoder 1080p@30fps with software.
• Display: Supports RGB/LVDS/DSI/HDMI interface to 1920x1200 resolution. Four-lane MIPI DSI is integrated as well.
• Memory Controller: Support external memory interfaces to NAND Flash,SD/eMMC,Nor Flash and SDRAM port. SDRAM port can be configured to support LPDDR2,LPDDR3,DDR3,DDR3L.
• HawkView^{TM} ISP: Support camera up to 8MPixels@30fps,better spatial de-noise and chrominance de-noise, Zone-based AE/AF/AWB statistics, Programmable color correction, Anti-flick detection statistics.

To reduce total system cost and enhance overall functionality,H8 has a broad range of hardware peripherals such as MIPI CSI,LCD controller, Power management, DMA, Timers, High Speed Timer, Security System, GPIO, Digital Audio,UART,SPI,CIR,USB2.0,TWI etc.

2. FEATURE

2.1.   CPU Architecture

• ARMv7 ISA standard instruction set plus Thumb-2 and Jazeller RCT
• NEON with SIMD and VFPv4
• Support LPAE
• 32KB I-cache and 32KB D-cache per CPU
• 1MB L2-cache

2.2.   GPU Architecture

• PowerVR SGX544MP1
• Support OpenGL ES 1.1/2.0
• Support OpenCL 1.1
• Support Directx 9.3 standards
• Support RenderScript

2.3.   Memory Subsystem

Boot ROM
• Size:96KB
• Support secure and non-secure boot
• Support system boot from Raw NAND, eMMC, SD/TF card and SPI Nor Flash
• Support system code download through USB OTG

SDRAM
• Compatible with JEDEC standard LPDDR2/LPDDR3/DDR3/DDR3L SDRAM
• Up to 2GB address space
• 16 address signal lines and 3 bank signal lines
• 32-bit bus width
• Support Memory Dynamic Frequency Scale

NAND Flash
• Up to 4 flash chips
• 8-bit data BUS width
• 64-bit ECC per 1024 bytes
• Support 1024,2048,4096,8192,16K bytes size per page
• Support SDR,ONFI DDR and Toggle DDR NAND

SD/MMC Interface
• Up to three SD/MMC controllers
• 1/4/8-bit SD,SDIO,MMC mode
• Compatible with eMMC standard specification V4.41, SD physical layer specification V2.0, SDIO card specification V2.0
• Data rate up to 100Mbps
• Support SDIO suspend and resume operation
• Support hardware CRC generation and error detection

- Support SDIO interrupt detection
- Support block size from 1 to 65535 bytes

2.4.   System Peripheral

Timer
- Two on-chip timers with interrupt-based operation
- 33-bit Audio/Video Sync Counter
- One watchdog to generate reset signal or interrupts
- 24MHz or Internal OSC clock input

High Speed Timer
- Counters up to 56bits
- Clock source is synchronized with AHB clock, much more accurate than other timers

OSC24M
- Support 1.8v oscillator
- Support internal RC oscillator

GIC
- Support 16 SGIs(Software Generated Interrupt), 16 PPIs(Private Peripheral Interrupt) and 168 SPIs(Shared Peripheral Interrupts)

DMA
- 8-channel DMA
- Flexible data width of 8/16/32 bits
- Support linear and IO address modes
- Support data transfer types with memory-to-memory, memory-to-peripheral, peripheral-to-memory

CCU
- 11 PLLs
- Support a 24MHz oscillator and an on-chip RC oscillator
- Clock configuration for corresponding modules
- Support software-controlled clock gating and software-controlled reset for corresponding modules

PWM
- Up to two PWM channels
- Support outputting two kinds of waveform: continuous waveform and pulse waveform
- 0% to 100% adjustable duty cycle
- Up to 24MHz output frequency

Security System
- Support symmetrical algorithm: AES, DES, TDES
- Support asymmetrical algorithm:RSA512/1024/2048/3072-bits
- Support hash algorithm:SHA-1/SHA-224/SHA-256, MD5
- 160-bits hardware PRNG with 192-bits seed
- 256-bits TRNG
- 32-bits hardware CRC
- Support ECB,CBC,CTR modes for DES/TDES
- Support ECB, CBC, CTR,CTS modes for AES
- 128-bits, 192-bits and 256-bits key size for AES

Security ID
• Support 2k-bits EFUSE for chip ID and security application

TrustZone
• Support TrustZone technology
• Support 96KB security SRAM

CPU Configuration
• Support power clamp
• Flexible CPU configuration

Power Management
• Support DVFS for CPU frequency and voltage adjustment
• Flexible clock gate and module reset
• Support dynamic frequency adjustment for external DRAM
• Support multiple power domains

2.5.   Display Subsystem

Display Engine2.0
• Input layer size up to 2048x2048, and output size up to 2048x2048
• Support four alpha blending channel for main display, two channel for aux display
• Support four overlay layers in each channel, and has a independent scaler
• Support potter-duff compatible blending operation
• Support input format YUV422/YUV420/YUV411/ARGB8888/XRGB8888/RGB888/ARGB4444/ARGB1555 and RGB565
• Support Frame Packing/Top-and-Bottom/Side-by-Side Full/Side-by-Side Half 3D format data
• Support display enhancement 2.0 for excellent display experience
    - Adaptive edge sharping
    - Adaptive color enhancement
    - Adaptive contrast enhancement and fresh tone rectify
• Support write back & rotation for high efficient dual display and miracast

Video Output
• Support two independent display channels
• Support RGB(24bits) up to 1920x1200@60Hz resolution
• Support RGB666/656 ditcher function
• Support LVDS up to 1366x768@60Hz resolution
• Support 4-lane MIPI DSI(V1.0) up to 1920x1200@60Hz resolution
• Support HDMI V1.4 output with HDCP1.2 up to 1920x1080@60Hz resolution

2.6.   Video Engine

Video Decoding
• Support multi-format video decoder, including:
    - MPEG1 MP/HL up to 1080p@60fps
    - MPEG2 MP/HL up to 1080p@60fps
    - MPEG4 SP/ASP up to 1080p@60fps
    - H.263 BP up to 1080p@60fps
    - H.264 BP/MP/HP up to 4K@24fps or 1080p@60fps
    - VP8 up to 1080p@60fps
    - VC1 SP/MP/AP up to 1080p@30fps

- JPEG/MJPEG up to 1080p@30fps
- Support HEVC/H.265 decoder(software),Main Profile,1080p@30fps

Video Encoding
- Support H.264 video encoding up to 1080p@60fps,720p@120fps
- JPEG baseline: picture size up to 8192x8192
- Support input picture size up to 4800x4800
- Support input format: tiled(128x32)/YU12/YV12/NU12/NV12/ARGB/YUYV
- Support Alpha blending
- Support thumb generation
- Support 4x2 scaling ratio: from 1/16 to 64 arbitrary non-integer ratio
- Support rotated input

2.7. Image Subsystem

CSI
- Support 10-bits parallel camera sensor
- Support up to 5M pixel camera sensor
- Support video shot up to 720p@30fps

MIPI CSI
- 4-lane MIPI CSI
- Support up to 8M pixel camera sensor
- Support video shot up to 1080p@60fps

ISP
- Support input formats:8/10-bits RAW RGB,8-bits YCbCr
- Support output formats: YCbCr420 semi-planar,YCrCb420 semi-planar, YCbCr422 semi-planar,YCrCb422 semi-planar,YUV420 planar,YUV422 Planar
- Support image mirror flip and rotation
- Support two output channels
- Speed up to 8MPixels@30fps
- Defect pixel correction
- Super lens shading correction
- Anisotropic non-linear Bayer interpolation with false color suppression
- Programmable color correction
- Advanced contrast enhance and sharping
- Advanced saturation adjust
- Advanced spatial(2D) de-noise filter
- Advanced chrominance noise reduction
- Zone-based AE/AF/AWB statistics
- Anti-flick detection statistics
- Histogram statistics

2.8. External Peripherals

USB
- USB 2.0 OTG
  - Complies with USB2.0 Specification
  - Support High-Speed(HS,480Mbps),Full-Speed(FS,12Mbps),and Low-Speed(LS,1.5Mbps) in Host mode
  - Up to 10 User-Configurable Endpoints
  - Support point-to-point and point-to-multipoint transfer in both Host and Peripheral mode

- Two EHCI/OHCI compliant Host SIE multiplexed with one USB 2.0 analog PHY, one HSIC PHY
  - Support High-Speed(HS,480Mbps),Full-Speed(FS,12Mbps),and Low-Speed(LS,1.5Mbps) Device
  - An internal DMA Controller for data transfer with memory

EMAC
- Support 10/100/1000Mbps data transfer rate
- Support MII/RGMII PHY interface
- Support full-duplex and half-duplex operation
- Programmable frame length
- Flexible address filtering modes
- Automatic CRC and pad generation controllable on a per-frame basis
- Options for Automatic Pad/CRC Stripping on receive frames
- Programmable frame length to support Standard or Jumbo Ethernet frames with sizes up to 16 KB
- Programmable Inter Frame Gap (40-96 bit times in steps of 8)
- Supports a variety of flexible address filtering modes

LRADC
- LRADC with 6-bit resolution
- Support hold key and continuous key
- Support single key, normal key and continuous key

Digital Audio
- PCM/I2S
  - I2S and PCM are configurable through software
  - Support I2S formats: normal, left-justified, right-justified
  - Audio data resolution:16bits, 20bits, 24bits
  - Audio sample rate up to 192KHz
  - Master and slave work mode are configurable
- TDM(Time Division Multiplexing)
  - Master/Slave mode
  - Audio sample resolution from 8bits to 32bits
  - Sample rate from 8KHz to 192KHz
  - 4 data output pin
  - DMA-based or interrupt-based operation
- OWA(One Wire Audio)
  - Support channel status insertion for the transmitter
  - 32x24bits TX FIFO for audio data transfer
  - Programmable FIFO thresholds

CIR
- A flexible receiver for IR remote
- Programmable FIFO thresholds

UART
- Up to six UART controllers
- 64-Bytes Transmit and receive data FIFOs for all UART
- Compliant with industry-standard 16550 UARTs
- Support Infrared Data Association(IrDA) 1.0 SIR

SPI
- Up to two SPI controllers
- Master/Slave configurable
- Mode0~3 are supported for both transmit and receive operation
- Two 64-Bytes FIFO for SPI-TX and SPI-RX operation
- DMA-based or interrupt-based operation

- Polarity and phase of the chip select(SPI_SS) and SPI_Clock(SPI_SCLK) are configurable

TWI
- Up to four TWI(Two Wire Interface) controllers
- Support Standard mode(up to 100K bps) and Fast mode(up to 400K bps)
- Master/Slave configurable
- Allows 10-bit addressing transactions

RSB^{TM}(Reduced Serial Bus)
- A simplified two wire protocol
- Support master mode
- Support multi-slaves
- Speed up to 20Mbps

2.9.   Package
- FBGA 345 balls,0.65mm ball pitch,14mm x14mm

3. BLOCK DIAGRAM

The following diagram shows the basic block diagram of H8.
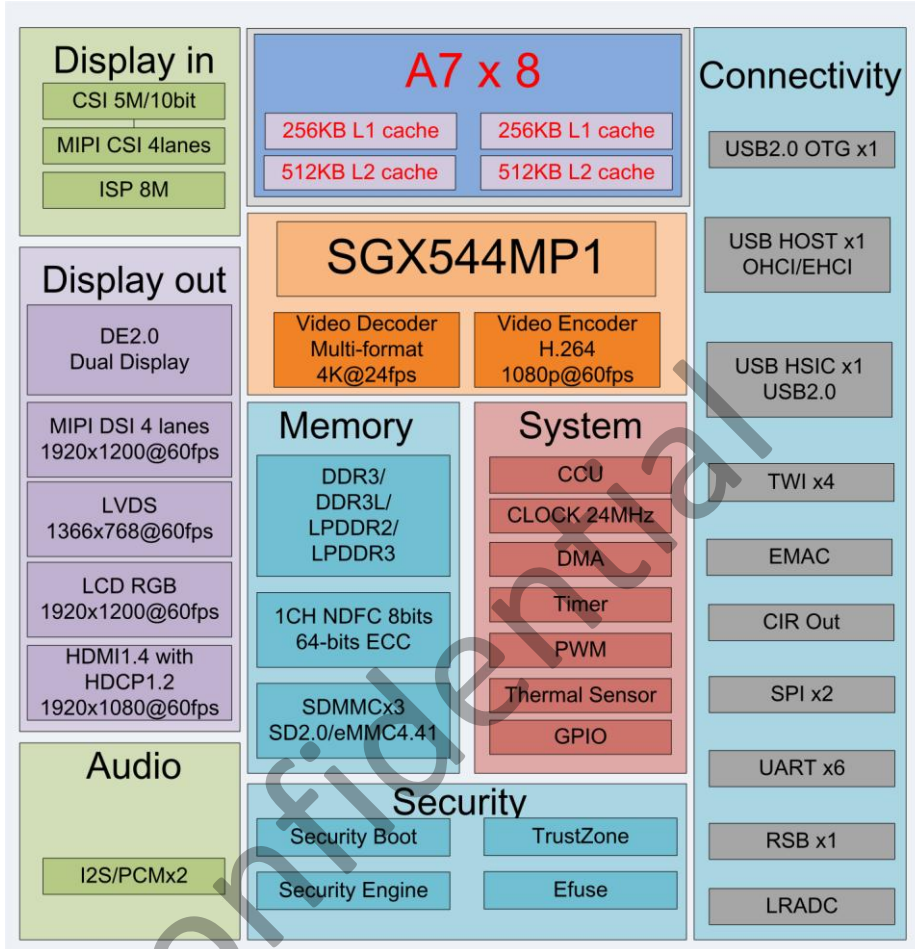
Figure 3-1.   H8 Block Diagram

4. PIN DESCRIPTION

4.1.   PIN CHARACTERISTICS

Table 4-1 lists the characteristics of H8 Pins from seven aspects: BALL#, Pin Name, Default Function, Type, Reset State, Default Pull Up/Down, and Buffer Strength.

✎ **NOTES**

1) **Default Function** defines the default function of each pin, especially for pins with multiplexing functions;
2) **Type** defines the signal direction: I (Input), O (Output), I/O(Input / Output), A (Analog), P (Power), G (Ground);
3) **Reset State** defines the state of the terminal at reset: Z for high-impedance, F for Multiplexing Functions Pin;
4) **Default Pull Up/Down** defines the presence of an internal pull up or pull down resister. Unless otherwise specified, the pin is default to be floating, and can be configured as pull up or pull down;
5) **Buffer Strength** defines drive strength of the associated output buffer. It is tested in the condition that VCC= 3.3V, strength=MAX;

Table 4-1 Pin Characteristics

Ball#	Pin Name©	Default Function©	Type©	Reset State©	Default Pull Up/Down©	Buffer Strength© (mA)
DRAM						
N4	SA0	DRAM	O	Z	-	-
M5	SA1	DRAM	O	Z	-	-
M4	SA2	DRAM	O	Z	-	-
L3	SA3	DRAM	O	Z	-	-
K3	SA4	DRAM	O	Z	-	-
J3	SA5	DRAM	O	Z	-	-
H2	SA6	DRAM	O	Z	-	-
H3	SA7	DRAM	O	Z	-	-
G3	SA8	DRAM	O	Z	-	-
G4	SA9	DRAM	O	Z	-	-
P3	SA10	DRAM	O	Z	-	-
U3	SA11	DRAM	O	Z	-	-
R5	SA12	DRAM	O	Z	-	-
G5	SA13	DRAM	O	Z	-	-
V4	SA14	DRAM	O	Z	-	-
R4	SA15	DRAM	O	Z	-	-
D6	SADBG	DRAM	A	Z	-	-
G2	SBA0	DRAM	O	Z	-	-
T4	SBA1	DRAM	O	Z	-	-
G1	SBA2	DRAM	O	Z	-	-
F2	SCAS	DRAM	O	Z	-	-
J1	SCK	DRAM	O	Z	-	-
J2	SCKB	DRAM	O	Z	-	-
J4	SCKE0	DRAM	O	Z	-	-
J5	SCKE1	DRAM	O	Z	-	-
K2	SCS0	DRAM	O	Z	-	-

Ball#	Pin Name©	Default Function©	Type©	Reset State©	Default Pull Up/Down©	Buffer Strength© (mA)
K4	SCS1	DRAM	O	Z	-	-
E6	SDDBG0	DRAM	A	Z	-	-
D7	SDDBG1	DRAM	A	Z	-	-
R2	SDQ0	DRAM	I/O	Z	-	-
R1	SDQ1	DRAM	I/O	Z	-	-
P2	SDQ2	DRAM	I/O	Z	-	-
N3	SDQ3	DRAM	I/O	Z	-	-
M1	SDQ4	DRAM	I/O	Z	-	-
M2	SDQ5	DRAM	I/O	Z	-	-
M3	SDQ6	DRAM	I/O	Z	-	-
L2	SDQ7	DRAM	I/O	Z	-	-
Y1	SDQ8	DRAM	I/O	Z	-	-
W2	SDQ9	DRAM	I/O	Z	-	-
W1	SDQ10	DRAM	I/O	Z	-	-
V3	SDQ11	DRAM	I/O	Z		
U2	SDQ12	DRAM	I/O	Z	-	-
T3	SDQ13	DRAM	I/O	Z	-	-
T2	SDQ14	DRAM	I/O	Z	-	-
T1	SDQ15	DRAM	I/O	Z	-	-
E2	SDQ16	DRAM	I/O	Z	-	-
D2	SDQ17	DRAM	I/O	Z	-	-
D1	SDQ18	DRAM	I/O	Z	-	-
D3	SDQ19	DRAM	I/O	Z	-	-
A2	SDQ20	DRAM	I/O	Z	-	-
B2	SDQ21	DRAM	I/O	Z	-	-
B1	SDQ22	DRAM	I/O	Z	-	-
A3	SDQ23	DRAM	I/O	Z	-	-
A4	SDQ24	DRAM	I/O	Z	-	-
B4	SDQ25	DRAM	I/O	Z	-	-
C4	SDQ26	DRAM	I/O	Z	-	-
B5	SDQ27	DRAM	I/O	Z	-	-
C6	SDQ28	DRAM	I/O	Z	-	-
A7	SDQ29	DRAM	I/O	Z	-	-
B8	SDQ30	DRAM	I/O	Z	-	-
B7	SDQ31	DRAM	I/O	Z	-	-
R3	SDQM0	DRAM	O	Z	-	-
Y2	SDQM1	DRAM	O	Z	-	-
F3	SDQM2	DRAM	O	Z	-	-
B3	SDQM3	DRAM	O	Z	-	-
N1	SDQS0	DRAM	I/O	Z	-	-
N2	SDQS0B	DRAM	I/O	Z	-	-

Ball#	Pin Name©	Default Function©	Type©	Reset State©	Default Pull Up/Down©	Buffer Strength© (mA)
V1	SDQS1	DRAM	I/O	Z	-	-
V2	SDQS1B	DRAM	I/O	Z	-	-
C1	SDQS2	DRAM	I/O	Z	-	-
C2	SDQS2B	DRAM	I/O	Z	-	-
B6	SDQS3	DRAM	I/O	Z	-	-
A6	SDQS3B	DRAM	I/O	Z	-	-
E3	SODT0	DRAM	O	Z	-	-
F4	SODT1	DRAM	O	Z	-	-
D4	SRAS	DRAM	O	Z	-	-
C5	SRST	DRAM	O	Z	-	-
K1	SVREF	DRAM	P	Z	-	-
F1	SWE	DRAM	O	Z	-	-
T5	SZQ	DRAM	A	Z	-	-
E7,F7,R6,J6,K6,L6,M6,N6,P6	VCC-DRAM	POWER	P	-	-	-
N8	VDD-SPLL	POWER	P	-	-	-

GPIO B

Ball#	Pin Name	Default Function	Type	Reset State	Default Pull Up/Down	Buffer Strength (mA)
D10	PB0	GPIO	I/O	Z	NO PULL	20
E10	PB1	GPIO	I/O	Z	NO PULL	20
B11	PB2	GPIO	I/O	Z	NO PULL	20
B10	PB3	GPIO	I/O	Z	NO PULL	20
C9	PB4	GPIO	I/O	Z	NO PULL	20
A10	PB5	GPIO	I/O	Z	NO PULL	20
E9	PB6	GPIO	I/O	Z	NO PULL	20
B9	PB7	GPIO	I/O	Z	NO PULL	20
C8	PB8	GPIO	I/O	Z	NO PULL	20
A9	PB9	GPIO	I/O	Z	NO PULL	20
D9	PB10	GPIO	I/O	Z	NO PULL	20
F9,L13,T7	VCC-IO	POWER	P	-	-	

GPIO C

Ball#	Pin Name	Default Function	Type	Reset State	Default Pull Up/Down	Buffer Strength (mA)
Y13	PC0	GPIO	I/O	Z	NO PULL	20
V12	PC1	GPIO	I/O	Z	NO PULL	20
AA13	PC2	GPIO	I/O	Z	NO PULL	20
W12	PC3	GPIO	I/O	Z	Pull-up	20
Y12	PC4	GPIO	I/O	Z	Pull-up	20
AA12	PC5	GPIO	I/O	Z	NO PULL	20
W11	PC6	GPIO	I/O	Z	Pull-up	20
Y11	PC7	GPIO	I/O	Z	Pull-up	20
T10	PC8	GPIO	I/O	Z	NO PULL	20
U10	PC9	GPIO	I/O	Z	NO PULL	20
V10	PC10	GPIO	I/O	Z	NO PULL	20
W10	PC11	GPIO	I/O	Z	NO PULL	20

Ball#	Pin Name[©]	Default Function[©]	Type[©]	Reset State[©]	Default Pull Up/Down[©]	Buffer Strength[©] (mA)
Y10	PC12	GPIO	I/O	Z	NO PULL	20
AA10	PC13	GPIO	I/O	Z	NO PULL	20
T9	PC14	GPIO	I/O	Z	NO PULL	20
V9	PC15	GPIO	I/O	Z	NO PULL	20
W9	PC16	GPIO	I/O	Z	NO PULL	20
Y9	PC17	GPIO	I/O	Z	Pull-up	20
AA9	PC18	GPIO	I/O	Z	Pull-up	20
GPIO D						
A20	PD2	GPIO	I/O	Z	NO PULL	20
B20	PD3	GPIO	I/O	Z	NO PULL	20
D18	PD4	GPIO	I/O	Z	NO PULL	20
D19	PD5	GPIO	I/O	Z	NO PULL	20
B21	PD6	GPIO	I/O	Z	NO PULL	20
C20	PD7	GPIO	I/O	Z	NO PULL	20
C21	PD10	GPIO	I/O	Z	NO PULL	20
D20	PD11	GPIO	I/O	Z	NO PULL	20
D21	PD12	GPIO	I/O	Z	NO PULL	20
E19	PD13	GPIO	I/O	Z	NO PULL	20
E20	PD14	GPIO	I/O	Z	NO PULL	20
F18	PD15	GPIO	I/O	Z	NO PULL	20
A15	PD18	GPIO	I/O	Z	NO PULL	20
B15	PD19	GPIO	I/O	Z	NO PULL	20
A16	PD20	GPIO	I/O	Z	NO PULL	20
B16	PD21	GPIO	I/O	Z	NO PULL	20
B17	PD22	GPIO	I/O	Z	NO PULL	20
C16	PD23	GPIO	I/O	Z	NO PULL	20
A18	PD24	GPIO	I/O	Z	NO PULL	20
B18	PD25	GPIO	I/O	Z	NO PULL	20
A19	PD26	GPIO	I/O	Z	NO PULL	20
B19	PD27	GPIO	I/O	Z	NO PULL	20
C17	PD28	GPIO	I/O	Z	NO PULL	20
C18	PD29	GPIO	I/O	Z	NO PULL	20
F13,F14	VCC-PD	POWER	P	-	-	-
F12	VCC18-LVDS	POWER	P	-	-	-
GPIO E						
E15	PE0	GPIO	I/O	Z	NO PULL	20
E16	PE1	GPIO	I/O	Z	NO PULL	20
D16	PE2	GPIO	I/O	Z	NO PULL	20
C15	PE3	GPIO	I/O	Z	NO PULL	20
D15	PE4	GPIO	I/O	Z	NO PULL	20
F15	PE5	GPIO	I/O	Z	NO PULL	20

Ball#	Pin Name[©]	Default Function[©]	Type[©]	Reset State[©]	Default Pull Up/Down[©]	Buffer Strength[©] (mA)
E13	PE6	GPIO	I/O	Z	NO PULL	20
D13	PE7	GPIO	I/O	Z	NO PULL	20
B14	PE8	GPIO	I/O	Z	NO PULL	20
F17	PE9	GPIO	I/O	Z	NO PULL	20
C14	PE10	GPIO	I/O	Z	NO PULL	20
E12	PE11	GPIO	I/O	Z	NO PULL	20
C13	PE12	GPIO	I/O	Z	NO PULL	20
D12	PE13	GPIO	I/O	Z	NO PULL	20
C12	PE14	GPIO	I/O	Z	NO PULL	20
B13	PE15	GPIO	I/O	Z	NO PULL	20
A13	PE16	GPIO	I/O	Z	NO PULL	20
B12	PE17	GPIO	I/O	Z	NO PULL	20
A12	PE18	GPIO	I/O	Z	NO PULL	20
C10	PE19	GPIO	I/O	Z	NO PULL	20
GPIO F						
Y5	PF0	GPIO	I/O	F	NO PULL	20
Y4	PF1	GPIO	I/O	F	NO PULL	20
AA4	PF2	GPIO	I/O	Z	NO PULL	20
W4	PF3	GPIO	I/O	F	NO PULL	20
AA3	PF4	GPIO	I/O	Z	NO PULL	20
Y3	PF5	GPIO	I/O	F	NO PULL	20
AA2	PF6	GPIO	I/O	Z	NO PULL	20
GPIO G						
K17	PG0	GPIO	I/O	Z	NO PULL	20
K18	PG1	GPIO	I/O	Z	NO PULL	20
L19	PG2	GPIO	I/O	Z	NO PULL	20
M16	PG3	GPIO	I/O	Z	NO PULL	20
M17	PG4	GPIO	I/O	Z	NO PULL	20
M18	PG5	GPIO	I/O	Z	NO PULL	20
M19	PG6	GPIO	I/O	Z	NO PULL	20
N16	PG7	GPIO	I/O	Z	NO PULL	20
N18	PG8	GPIO	I/O	Z	NO PULL	20
N19	PG9	GPIO	I/O	Z	NO PULL	20
N20	PG10	GPIO	I/O	Z	NO PULL	20
N21	PG11	GPIO	I/O	Z	NO PULL	20
P19	PG12	GPIO	I/O	Z	NO PULL	20
R18	PG13	GPIO	I/O	Z	NO PULL	20
GPIO H						
U9	PH0	GPIO	I/O	Z	NO PULL	20
W8	PH1	GPIO	I/O	Z	NO PULL	20
Y8	PH2	GPIO	I/O	Z	NO PULL	20

Ball#	Pin Name©	Default Function©	Type©	Reset State©	Default Pull Up/Down©	Buffer Strength© (mA)
AA7	PH3	GPIO	I/O	Z	NO PULL	20
Y7	PH4	GPIO	I/O	Z	NO PULL	20
W7	PH5	GPIO	I/O	Z	NO PULL	20
V7	PH6	GPIO	I/O	Z	NO PULL	20
AA6	PH7	GPIO	I/O	Z	NO PULL	20
U7	PH8	GPIO	I/O	Z	NO PULL	20
Y6	PH9	GPIO	I/O	Z	NO PULL	20
W6	PH10	GPIO	I/O	Z	NO PULL	20
V6	PH11	GPIO	I/O	Z	NO PULL	20
GPIO L						
AA15	PL0	GPIO	I/O	Z	Pull-up	20
W14	PL1	GPIO	I/O	Z	Pull-up	20
W16	PL2	GPIO	I/O	Z	NO PULL	20
V16	PL3	GPIO	I/O	Z	NO PULL	20
V15	PL4	GPIO	I/O	Z	NO PULL	20
W17	PL5	GPIO	I/O	Z	NO PULL	20
Y17	PL6	GPIO	I/O	Z	NO PULL	20
U16	PL7	GPIO	I/O	Z	NO PULL	20
AA18	PL8	GPIO	I/O	Z	NO PULL	20
Y18	PL9	GPIO	I/O	Z	NO PULL	20
W18	PL10	GPIO	I/O	Z	NO PULL	20
V18	PL11	GPIO	I/O	Z	NO PULL	20
AA19	PL12	GPIO	I/O	Z	NO PULL	20
T15	VCC-PL	POWER	P	-	-	-
System Control						
U15	UBOOT	-	I	-	Pull-up	-
W5	JTAGSEL	-	I	-	Pull-up	-
Y14	TEST	-	I	-	Pull-down	-
Y16	NMI	-	I	Z	-	-
AA16	RESET	-	I	Z	-	-
U13	VCC18-EFUSE	-	P	-	-	-
HDMI						
J18	HHPD	-	A	-	-	-
L20	HTX0N	-	A	-	-	-
K19	HTX0P	-	A	-	-	-
K21	HTX1N	-	A	-	-	-
K20	HTX1P	-	A	-	-	-
J21	HTX2N	-	A	-	-	-
J20	HTX2P	-	A	-	-	-
M21	HTXCN	-	A	-	-	-
M20	HTXCP	-	A	-	-	-

Ball#	Pin Name[©]	Default Function[©]	Type[©]	Reset State[©]	Default Pull Up/Down[©]	Buffer Strength[©] (mA)
K14	VCC18-HDMI	-	P	-	-	-
K13	VDD09-HDMI	-	P	-	-	-
USB						
W20	USB0-DM	-	A	-	-	-
W21	USB0-DP	-	A	-	-	-
Y21	USB0- ID	-	A	-	-	-
Y19	USB0-VBUS	-	A	-	-	-
AA20	USB1-DM	-	A	-	-	-
Y20	USB1-DP	-	A	-	-	-
R16	VCC33-USB	-	P	-	-	-
P13	VDD09-USB	-	P	-	-	-
HSIC						
V21	HSIC-DATA	-	A	-	-	-
V20	HSIC-STRB	-	A	-	-	-
P14	VCC12-HSIC	-	P	-	-	-
ADC						
W15	LRADC0	-	A	-	-	-
T14	GND-ADC	-	G			
MCSI						
T21	MCSI-CKN	-	A	-	-	-
T20	MCSI-CKP	-	A	-	-	-
U19	MCSI-DN0	-	A	-	-	-
T19	MCSI-DN1	-	A	-	-	-
R21	MCSI-DN2	-	A	-	-	-
P20	MCSI-DN3	-	A	-	-	-
V19	MCSI-DP0	-	A	-	-	-
U20	MCSI-DP1	-	A	-	-	-
R20	MCSI-DP2	-	A	-	-	-
R19	MCSI-DP3	-	A	-	-	-
N13	VCC18-MCSI	-	P	-	-	-
MDSI						
G18	MDSI-CKN	-	A	-	-	-
G19	MDSI-CKP	-	A	-	-	-
H20	MDSI-DN0	-	A	-	-	-
G20	MDSI-DN1	-	A	-	-	-
F21	MDSI-DN2	-	A	-	-	-
F19	MDSI-DN3	-	A	-	-	-
J19	MDSI-DP0	-	A	-	-	-
H19	MDSI-DP1	-	A	-	-	-
G21	MDSI-DP2	-	A	-	-	-
F20	MDSI-DP3	-	A	-	-	-

Ball#	Pin Name[©]	Default Function[©]	Type[©]	Reset State[©]	Default Pull Up/Down[©]	Buffer Strength[©] (mA)
H13	VCC18-MDSI	-	P	-	-	-
RTC&PLL						
W13	REXT	-	A	-	-	-
Y15	RTC-VIO	-	P	-	-	-
U12	X24MI	-	A	-	-	-
V13	X24MO	-	A	-	-	-
Other						
M10	VDDFB-CPUA	-	I/O	-	-	-
J12	VDDFB-CPUB	-	I/O	-	-	-
Power						
T12	VCC18-PLL	-	P	-	-	-
T13	VCC18-ADC	-	P	-	-	-
F8,L14,T8	VDD18	-	P	-	-	-
L9,L10,L11,L12,M9,M11,M12,M13,M14	VDD-CPUA	-	P	-	-	-
F10,F11,H9,H10,H11,J9,J10, J11	VDD-CPUB	-	P	-	-	-
R17,T17	VDD-CPUS	-	P	-	-	-
P9,P10,P11,T11	VDD-GPU	-	P	-	-	-
J14,J16,K16	VDD-SYS	-	P	-	-	-
A1,A21,C7,C11,F5,G6,G16,G17,H8,H12,H14,H16,J8,J13,J17,K5,K8,K9,K10,K11,K12,L8,L16,M8,N5,N9,N10,N11,N12,N14,N17,P8,P12,P16,H6,U6,T18,AA1,AA21	GND(39)	-	G	-	-	-

4.2. GPIO MULTIPLEXING FUNCTIONS

The following table provides a description of the H8 GPIO multiplexing functions.

Table 4-2 Multiplexing Functions

Pin Name	Default Function	IO Type	Default IO State	Default Pull-up/ down	Function 2	Function3	Function 4	Function 5	Function 6
PB0		I/O	DIS	Z	UART2_TX	JTAG_MS0	-	-	PB_EINT0
PB1		I/O	DIS	Z	UART2_RX	JTAG_CK0	-	-	PB_EINT1
PB2		I/O	DIS	Z	UART2_RTS	JTAG_DO0	-	-	PB_EINT2
PB3	GPIO	I/O	DIS	Z	UART2_CTS	JTAG_DI0	-	-	PB_EINT3
PB4		I/O	DIS	Z	I2S0_LRCK	TDM_LRCK	-	-	PB_EINT4
PB5		I/O	DIS	Z	I2S0_BCLK	TDM_BCLK	-	-	PB_EINT5
PB6		I/O	DIS	Z	I2S0_DOUT	TDM_DOUT	-	-	PB_EINT6

Pin Name	Default Function	IO Type	Default IO State	Default Pull-up/down	Function 2	Function3	Function 4	Function 5	Function 6
PB7		I/O	DIS	Z	I2S0_DIN	TDM_DIN	-	-	PB_EINT7
PB8		I/O	DIS	Z	I2S0_MCLK	TDM_MCLK	-	-	PB_EINT8
PB9		I/O	DIS	Z	UART0_TX	-	-	-	PB_EINT9
PB10		I/O	DIS	Z	UART0_RX	-	-	-	PB_EINT10
PC0		I/O	DIS	Z	NAND_WE	SPI0_MOSI	-	-	-
PC1		I/O	DIS	Z	NAND_ALE	SPI0_MISO	-	-	-
PC2		I/O	DIS	Z	NAND_CLE	SPI0_CLK	-	-	-
PC3		I/O	DIS	Pull-up	NAND_CE1	SPI0_CS	-	-	-
PC4		I/O	DIS	Pull-up	NAND_CE0	-	-	-	-
PC5		I/O	DIS	Z	NAND_RE	SDC2_CLK	-	-	-
PC6		I/O	DIS	Pull-up	NAND_RB0	SDC2_CMD	-	-	-
PC7		I/O	DIS	Pull-up	NAND_RB1	-	-	-	-
PC8		I/O	DIS	Z	NAND_DQ0	SDC2_D0	-	-	-
PC9	GPIO	I/O	DIS	Z	NAND_DQ1	SDC2_D1	-	-	-
PC10		I/O	DIS	Z	NAND_DQ2	SDC2_D2	-	-	-
PC11		I/O	DIS	Z	NAND_DQ3	SDC2_D3	-	-	-
PC12		I/O	DIS	Z	NAND_DQ4	SDC2_D4	-	-	-
PC13		I/O	DIS	Z	NAND_DQ5	SDC2_D5	-	-	-
PC14		I/O	DIS	Z	NAND_DQ6	SDC2_D6	-	-	-
PC15		I/O	DIS	Z	NAND_DQ7	SDC2_D7	-	-	-
PC16		I/O	DIS	Z	NAND_DQS	SDC2_RST	-	-	-
PC17		I/O	DIS	Pull-up	NAND_CE2	-	-	-	-
PC18		I/O	DIS	Pull-up	NAND_CE3	-	-	-	-
PD2		I/O	DIS	Z	LCD_D2	-	RGMII-RXD3 /MII-RXD3	-	-
PD3		I/O	DIS	Z	LCD_D3	-	RGMII-RXD2 /MII-RXD2	-	-
PD4		I/O	DIS	Z	LCD_D4	-	RGMII-RXD1 /MII-RXD1	-	-
PD5		I/O	DIS	Z	LCD_D5	-	RGMII-RXD0 /MII-RXD0	-	-
PD6		I/O	DIS	Z	LCD_D6	-	RGMII-RXCK /MII-RXCK	-	-
PD7		I/O	DIS	Z	LCD_D7	-	RGMII-RXCTL/MII-RXDV	-	-
PD10	GPIO	I/O	DIS	Z	LCD_D10	-	RGMII-NULL /MII-RXERR	-	-
PD11		I/O	DIS	Z	LCD_D11	-	RGMII-TXD3 /MII-TXD3	-	-
PD12		I/O	DIS	Z	LCD_D12	-	RGMII-TXD2 /MII-TXD2	-	-
PD13		I/O	DIS	Z	LCD_D13	-	RGMII-TXD1 /MII-TXD1	-	-
PD14		I/O	DIS	Z	LCD_D14	-	RGMII-TXD0 /MII-TXD0	-	-
PD15		I/O	DIS	Z	LCD_D15	-	RGMII-NULL /MII-CRS	-	-
PD18		I/O	DIS	Z	LCD_D18	LVDS_VP0	RGMII-TXCK /MII-TXCK	-	-

Pin Name	Default Function	IO Type	Default IO State	Default Pull-up/ down	Function 2	Function3	Function 4	Function 5	Function 6
PD19		I/O	DIS	Z	LCD_D19	LVDS_VN0	RGMII-TXCTL/MII-TXEN	-	-
PD20		I/O	DIS	Z	LCD_D20	LVDS_VP1	RGMII-NULL/MII-TXERR	-	-
PD21		I/O	DIS	Z	LCD_D21	LVDS_VN1	RGMII-CLKIN/MII-COL	-	-
PD22		I/O	DIS	Z	LCD_D22	LVDS_VP2	EMDC	-	-
PD23		I/O	DIS	Z	LCD_D23	LVDS_VN2	EMDIO	-	-
PD24		I/O	DIS	Z	LCD_CLK	LVDS_VPC	-	-	-
PD25		I/O	DIS	Z	LCD_DE	LVDS_VNC	-	-	-
PD26		I/O	DIS	Z	LCD_HSYNC	LVDS_VP3	-	-	-
PD27		I/O	DIS	Z	LCD_VSYNC	LVDS_VP3	-	-	-
PD28		I/O	DIS	Z	PWM	-	-	-	-
PD29		I/O	DIS	Z	-	-	-	-	-
PE0		I/O	DIS	Z	CSI_PCLK	-	CCIR-CLK	-	-
PE1		I/O	DIS	Z	CSI_MCLK	-	CCIR-DE	-	-
PE2		I/O	DIS	Z	CSI_HSYNC	-	CCIR-HSYNC	-	-
PE3		I/O	DIS	Z	CSI_VSYNC	-	CCIR-VSYNC	-	-
PE4		I/O	DIS	Z	CSI_D0	-	-	-	-
PE5		I/O	DIS	Z	CSI_D1	-	-	-	-
PE6		I/O	DIS	Z	CSI_D2	-	CCIR-D0	-	-
PE7		I/O	DIS	Z	CSI_D3	-	CCIR-D1	-	-
PE8		I/O	DIS	Z	CSI_D4	-	CCIR-D2	-	-
PE9		I/O	DIS	Z	CSI_D5	-	CCIR-D3	-	-
PE10	GPIO	I/O	DIS	Z	CSI_D6	UART4_TX	CCIR-D4	-	-
PE11		I/O	DIS	Z	CSI_D7	UART4_RX	CCIR-D5	-	-
PE12		I/O	DIS	Z	CSI_D8	UART4_RTS	CCIR-D6	-	-
PE13		I/O	DIS	Z	CSI_D9	UART4_CTS	CCIR-D7	-	-
PE14		I/O	DIS	Z	CSI_SCK	TWI2_SCK	-	-	-
PE15		I/O	DIS	Z	CSI_SDA	TWI2_SDA	-	-	-
PE16		I/O	DIS	Z	-	-	-	-	-
PE17		I/O	DIS	Z	-	-	-	-	-
PE18		I/O	DIS	Z	-	OWA_OUT	-	-	-
PE19		I/O	DIS	Z	-		-	-	-
PF0		I/O	DIS	F	SDC0_D1	JTAG_MS1	-	-	-
PF1		I/O	DIS	F	SDC0_D0	JTAG_DI1	-	-	-
PF2		I/O	DIS	Z	SDC0_CLK	UART0_TX	-	-	-
PF3	GPIO	I/O	DIS	F	SDC0_CMD	JTAG_DO1	-	-	-
PF4		I/O	DIS	Z	SDC0_D3	UART0_RX	-	-	-
PF5		I/O	DIS	F	SDC0_D2	JTAG_CK1	-	-	-
PF6		I/O	DIS	Z	-		-	-	-
PG0	GPIO	I/O	DIS	Z	SDC1_CLK	-	-	-	PG_EINT0
PG1		I/O	DIS	Z	SDC1_CMD	-	-	-	PG_EINT1

Pin Name	Default Function	IO Type	Default IO State	Default Pull-up/down	Function 2	Function3	Function 4	Function 5	Function 6
PG2		I/O	DIS	Z	SDC1_D0	-	-	-	PG_EINT2
PG3		I/O	DIS	Z	SDC1_D1	-	-	-	PG_EINT3
PG4		I/O	DIS	Z	SDC1_D2	-	-	-	PG_EINT4
PG5		I/O	DIS	Z	SDC1_D3	-	-	-	PG_EINT5
PG6		I/O	DIS	Z	UART1_TX	SPI1_CS	-	-	PG_EINT6
PG7		I/O	DIS	Z	UART1_RX	SPI1_CLK	-	-	PG_EINT7
PG8		I/O	DIS	Z	UART1_RTS	SPI1_MOSI	-	-	PG_EINT8
PG9		I/O	DIS	Z	UART1_CTS	SPI1_MISO	-	-	PG_EINT9
PG10		I/O	DIS	Z	I2S1_BCLK	UART3_TX	-	-	PG_EINT10
PG11		I/O	DIS	Z	I2S1_LRCK	UART3_RX	-	-	PG_EINT11
PG12		I/O	DIS	Z	I2S1_DOUT	UART3_RTS	-	-	PG_EINT12
PG13		I/O	DIS	Z	I2S1_DIN	UART3_CTS	-	-	PG_EINT13
PH0	GPIO	I/O	DIS	Z	TWI0_SCK	-	-	-	PH_EINT0
PH1		I/O	DIS	Z	TWI0_SDA	-	-	-	PH_EINT1
PH2		I/O	DIS	Z	TWI1_SCK	-	-	-	PH_EINT2
PH3		I/O	DIS	Z	TWI1_SDA	-	-	-	PH_EINT3
PH4		I/O	DIS	Z	TWI2_SCK	-	-	-	PH_EINT4
PH5		I/O	DIS	Z	TWI2_SDA	-	-	-	PH_EINT5
PH6		I/O	DIS	Z	HSCL	-	-	-	PH_EINT6
PH7		I/O	DIS	Z	HSDA	-	-	-	PH_EINT7
PH8		I/O	DIS	Z	HCEC	-	-	-	PH_EINT8
PH9		I/O	DIS	Z	-	-	-	-	PH_EINT9
PH10		I/O	DIS	Z	-	-	-	-	PH_EINT10
PH11		I/O	DIS	Z	-	-	-	-	PH_EINT11
PL0	GPIO	I/O	DIS	Pull-up	S_RSB_SCK	S_TWI_SCK	-	-	S_PL_EINT0
PL1		I/O	DIS	Pull-up	S_RSB_SDA	S_TWI_SDA	-	-	S_PL_EINT1
PL2		I/O	DIS	Z	S_UART_TX	-	-	-	S_PL_EINT2
PL3		I/O	DIS	Z	S_UART_RX	-	-	-	S_PL_EINT3
PL4		I/O	DIS	Z	S_JTAG_MS	-	-	-	S_PL_EINT4
PL5		I/O	DIS	Z	S_JTAG_CK	-	-	-	S_PL_EINT5
PL6		I/O	DIS	Z	S_JTAG_DO	-	-	-	S_PL_EINT6
PL7		I/O	DIS	Z	S_JTAG_DI	-	-	-	S_PL_EINT7
PL8		I/O	DIS	Z	S_TWI_SCK	-	-	-	S_PL_EINT8
PL9		I/O	DIS	Z	S_TWI_SDA	-	-	-	S_PL_EINT9
PL10		I/O	DIS	Z	S_PWM	-	-	-	S_PL_EINT10
PL11		I/O	DIS	Z	-	-	-	-	S_PL_EINT11
PL12		I/O	DIS	Z	S_CIR_RX	-	-	-	S_PL_EINT12

4.3.   DETAILED PIN/SIGNAL DESCRIPTION

Table 4-3 shows the pin/signal description of H8.

Table 4-3 Detailed Pin Description

Pin/Signal Name	Description	Type
DRAM		
SDQ[31:0]	DRAM DQ[31:0]	I/O
SDQS[3:0]	DRAM Data Strobe DQS[3:0]	I/O
SDQSB[3:0]	DRAM DQSB[3:0]	I/O
SDQM[3:0]	DRAM DQ Mask [3:0]	O
SCK	DRAM Clock	O
SCKB	DRAM CKB	O
SCKE[1:0]	DRAM Clock Enable [1:0]	O
SA[15:0]	DRAM data Address [15:0]	O
SWE	DRAM Write Enable	O
SCAS	DRAM Column Address Strobe	O
SRAS	DRAM Row Address Strobe	O
SCS[1:0]	DRAM Chip Select [1:0]	O
SBA[2:0]	DRAM Bank Address [2:0]	O
SODT[1:0]	DRAM ODT Control [1:0]	O
SRST	DRAM Reset	O
SZQ	DRAM ZQ Calibration	A
SVREF	DRAM Reference Input	P
VCC-DRAM	DRAM Power Supply	P
GND-DRAM	DRAM Ground	G
VDD-SPLL[2:0]	DLL Power Supply[2:0]	P
SDBG	DRAM DBG	A
System Control		
UBOOT	UBOOT	I
JTAGSEL	JTAG Mode Select	I
TEST	TEST Signal	I
VCC18-EFUSE	eFUSE Power Supply	P
NMI	Non-Maskable Interrupt	I
RESET	RESET Signal	I
HDMI		
HTX0P	TMDS Data 0 Positive	A
HTX0N	TMDS Data 0 Negative	A
HTX1P	TMDS Data 1 Positive	A
HTX1N	TMDS Data 1 Negative	A
HTX2P	TMDS Data 2 Positive	A
HTX2N	TMDS Data 2 Negative	A
HTXCP	TMDS Clock Positive	A
HTXCN	TMDS Clock Negative	A

Pin/Signal Name	Description	Type
VCC18-HDMI	HDMI Power Supply	P
VDD09-HDMI	HDMI Power Supply	P
HHPD	HDMI Hot Plug Detection signal	A
USB		
USB0-DM	USB DM Signal	A
USB0-DP	USB DP Signal	A
USB0-ID	USB ID Signal	A
USB0-VBUS	USB VBUS Signal	A
USB1-DM	USB DM Signal	A
USB1-DP	USB DP Signal	A
VCC33-USB	USB Power Supply	P
VDD09-USB	USB Power Supply	P
HSIC		
VCC12-HSIC	HSIC Power Supply	P
HSIC-STRB	USB HSIC Strobe Signal	A
HSIC-DATA	USB HSIC Data Signal	A
ADC		
LRADC0	LRADC input	A
VCC18-ADC	ADC Power Supply	P
MIPI DSI		
MDSI-DN0	MIPI DSI Data 0 Negative	A
MDSI-DP0	MIPI DSI Data 0 Positive	A
MDSI-DN1	MIPI DSI Data 1 Negative	A
MDSI-DP1	MIPI DSI Data 1 Positive	A
MDSI-DN2	MIPI DSI Data 2 Negative	A
MDSI-DP2	MIPI DSI Data 2 Positive	A
MDSI-DN3	MIPI DSI Data 3 Negative	A
MDSI-DP3	MIPI DSI Data 3 Positive	A
MDSI-CKN	MIPI DSI Clock Negative	A
MDSI-CKP	MIPI DSI Clock Positive	A
VCC18-MDSI	MIPI DSI Power Supply	P
MIPI CSI		
MCSI-DN0	MIPI CSI Data 0 Negative	A
MCSI-DP0	MIPI CSI Data 0 Positive	A
MCSI-DN1	MIPI CSI Data 1 Negative	A
MCSI-DP1	MIPI CSI Data 1 Positive	A
MCSI-DN2	MIPI CSI Data 2 Negative	A
MCSI-DP2	MIPI CSI Data 2 Positive	A
MCSI-DN3	MIPI CSI Data 3 Negative	A
MCSI-DP3	MIPI CSI Data 3 Positive	A
MCSI-CKN	MIPI CSI Clock Negative	A
MCSI-CKP	MIPI CSI Clock Positive	A

Pin/Signal Name	Description	Type
VCC18-MCSI	MIPI CSI Power Supply	P
RTC&PLL		
REXT	External Reference Register	A
RTC-VIO	Internal LDO Output Bypass	A
X24MI	Clock Input Of 24MHz Crystal	A
X24MO	Clock Output Of 24MHz Crystal	A
TEST	PLL Test Signal	A
VCC18-PLL	PLL Power Supply	P
SD /MMC(x=[2:0])		
SDCx_CMD	SDx/MMCx/SDIOx Command Signal	I/O
SDCx_CLK	SDx/MMCx/SDIOx Clock	O
SDC0_D[3:0]	SD0/MMC0/SDIO0 Data [3:0]	I/O
SDC1_D[3:0]	SD1/MMC1/SDIO1 Data [3:0]	I/O
SDC2_D[7:0]	SD2/MMC2/SDIO2 Data [7:0]	I/O
SDC2_RST	SD2/MMC2/SDIO2 Reset Signal	O
NAND FLASH		
NAND_DQ[7:0]	NAND Flash Data Bit [7:0]	I/O
NAND_DQS	NADN Flash Data Strobe	I/O
NAND_WE	NAND Flash Write Enable	O
NAND_RE	NAND Flash chip Read Enable	O
NAND_ALE	NAND Flash Address Latch Enable	O
NAND_CLE	NAND Command Latch Enable	O
NAND_CE[3:0]	NAND Flash Chip Select [3:0]	O
NAND_RB[1:0]	NAND Flash Ready/Busy Bit	I
RSB		
S_RSB_SCK	RSB Clock	I/O
S_RSB_SDA	RSB Data	I/O
Interrupt		
PB_EINT[10:0]	GPIO B Interrupt	I
PG_EINT[13:0]	GPIO G Interrupt	I
PH_EINT[11:0]	GPIO H Interrupt	I
S_PL_EINT[12:0]	GPIO L Interrupt	I
PWM		
S_PWM	Pulse Width Modulation Output	O
PWM	Pulse Width Modulation Output	O
IR		
S_IR_RX	IR Data Receive	I
LCD		
LCD0_D[23:0]	LCD Data Bit [23:0]	O
LCD_CLK	LCD Clock signal	O
LCD_DE	LCD Data Enable	O
LCD_HSYNC	LCD Horizontal SYNC	O

Pin/Signal Name	Description	Type
LCD_VSYNC	LCD Vertical SYNC	O
LVDS		
LVDS_VP[3:0]	LVDS Data Positive Signal Output[3:0]	A
LVDS_VN[3:0]	LVDS Data Negative Signal Output[3:0]	A
LVDS_VPC	LVDS Clock Positive Signal Output	A
LVDS_VNC	LVDS Clock Negative Signal Output	A
I2S (x=[1:0])		
I2S0_MCLK	I2S 0 Master Clock (system clock)	O
I2Sx_BCLK	I2S Bit Clock	I/O
I2Sx_LRCK	I2S Left/Right Channel Select Clock	I/O
I2Sx_DIN	I2Sx Data Input	I
I2Sx_DOUT	I2Sx Data Output	O
CSI		
CSI_PCLK	CSI Pixel Clock	I
CSI_MCLK	CSI Master Clock	O
CSI_HSYNC	CSI Horizontal SYNC	I
CSI_VSYNC	CSI Vertical SYNC	I
CSI_D[9:0]	CSI Data bit [9:0]	I
CSI_SCK	CSI Command Serial Clock Signal	I/O
CSI_SDA	CSI Command Serial Data Signal	I/O
EMAC		
RGMII-RXD[3:0]	MII Receive Data Nibble Data Bit[3:0]	I
RGMII-RXCK	MII Receive Clock	I
RGMII-RXCTL/MII-RXDV	MII Receive Control/EMAC Receive Data Valid	I
MII-RXERR	MII Receive Error	I
RGMII-TXD[3:0]	MII Transmit Data Nibble Data Bit[3:0]	O
MII-CRS	MII Carrier Sense	I
RGMII-TXCK/MII-TXCK	MII Transmit Clock	O
RGMII-TXCTL/MII-TXEN	MII Transmit Control/MII Transmit Enable	O
MII-TXERR	MII Transmit Error	O
RGMII-CLKIN/MII-COL	MII Clock Input/EMAC Collision Detect	I
EMDC	MII Management Data Clock	O
EMDIO	MII Management Data Input/Output	I/O
SPI (x=[1:0])		
SPIx_CS	SPIx Chip Select signal	I/O
SPIx_CLK	SPI Clock signal	I/O
SPIx_MOSI	SPI Master data Out, Slave data In	I/O
SPIx_MISO	SPI Master data In, Slave data Out	I/O
UART (x=[4:0])		
UARTx_CTS	UART Data Clear To Send	I
UARTx_RTS	UART Data Request To Send	O
UARTx_TX	UART Data Transmit	O

Pin/Signal Name	Description	Type
UARTx_RX	UART Data Receive	I
S_UART_TX	UART Data Transmit	O
S_UART_RX	UART Data Receive	I
TWI (x=[2:0])		
TWIx_SCK	TWI Serial Clock Signal	I/O
TWIx_SDA	TWI Serial Data Signal	I/O
S_TWI_SCK	TWI Serial Clock Signal	I/O
S_TWI_SDA	TWI Serial Data Signal	I/O

5. ELECTRICAL CHARACTERISTICS

5.1.　ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Table 5-1 specifies the absolute maximum ratings over the operating junction temperature range of commercial and extended temperature devices. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this standard may damage to the device.

Table 5-1　Absolute Maximum Ratings

Symbol	Parameter	MIN	Max	Unit
$I_{I/O}$	In/Out current for input and output	-40	40	mA
VDD18	Power Supply for System	-0.3	1.98	V
VDD-SYS	Power Supply for System	-0.3	1.3	V
VDD-CPUA	Power Supply for CPUA	-0.3	1.3	V
VDD-CPUB	Power Supply for CPUB	-0.3	1.3	V
VDD-CPUS	Power Supply for CPUS	-0.3	1.3	V
VCC-DRAM	Power Supply for DRAM	-0.3	1.65	V
VDD-SPLL	Power Supply for DRAM PLL	-0.3	1.98	V
VCC33-USB	Power Supply for USB	-0.3	3.6	V
VDD09-USB	Power Supply for USB	-0.3	1.3	V
VCC12-HSIC	Power Supply for HSIC	-0.3	1.32	V
VCC18-HDMI	Power Supply for HDMI	-0.3	1.98	V
VDD09-HDMI	Power Supply for HDMI	-0.3	1.3	V
VCC18-PLL	Power Supply for system PLL	-0.3	1.98	V
VCC18-ADC	Power Supply for HDMI	-0.3	1.98	V
VCC18-EFUSE	Power Supply for EFUSE	-0.3	1.98	V
VCC18-LDVS	Power Supply for LVDS	-0.3	1.98	V
VCC18-MCSI	Power Supply for MIPI-CSI	-0.3	1.98	V
VCC18-MDSI	Power Supply for MIPI-DSI	-0.3	1.98	V
VCC-IO	Power Supply for Port B	-0.3	3.6	V
VCC-PD	Power Supply for Port D	-0.3	3.6	V
VCC-PL	Power Supply for Port L	-0.3	3.6	V
VDD-GPU	Power Supply for GPU	-0.3	1.3	V
T_{STG}	Storage Temperature	-40	125	°C

5.2. RECOMMENDED OPERATING CONDITIONS

All H8 modules are used under the operating Conditions contained in Table 5-2.

Table 5-2   Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
Ta	Ambient Operating Temperature	-20	-	+70	°C
VDD18	Power Supply for System	1.62	1.8	1.98	V
VDD-SYS	Power Supply for System	0.7	0.9	1.1	V
VDD-CPUA	Power Supply for CPUA	0.7	0.9	1.1	V
VDD-CPUB	Power Supply for CPUB	0.7	0.9	1.1	V
VDD-CPUS	Power Supply for CPUS	0.7	0.9	1.1	V
VCC-DRAM	Power Supply for DRAM	1.14	1.2/1.35/1.5	1.575	V
VDD-SPLL	Power Supply for DRAM	1.62	1.8	1.98	V
VCC33-USB	Power Supply for USB	3.0	3.3	3.45	V
VDD09-USB	Power Supply for USB	0.7	0.9	1.1	V
VCC12-HSIC	Power Supply for HSIC	1.08	1.2	1.32	V
VCC18-HDMI	Power Supply for HDMI	1.62	1.8	1.98	V
VDD09-HDMI	Power Supply for HDMI	0.7	0.9	1.1	V
VCC18-PLL	Power Supply for PLL	1.62	1.8	1.98	V
VCC18-ADC	Power Supply for ADC	1.62	1.8	1.98	V
VCC18-EFUSE	Power Supply for ADC	1.62	1.8	1.98	V
VCC18-LDVS	Power Supply for LVDS	1.62	1.8	1.98	V
VCC18-MCSI	Power Supply for MCSI	1.62	1.8	1.98	V
VCC18-MDSI	Power Supply for MDSI	1.62	1.8	1.98	V
VCC-IO	Power Supply for Port B	1.7	1.8~3.3	3.6	V
VCC-PD	Power Supply for Port D	1.7	1.8~3.3	3.6	V
VCC-PL	Power Supply for Port L	1.7	1.8~3.3	3.6	V
VDD-GPU	Power Supply for GPU	0.7	0.9	1.1	V

5.3.　　DC ELECTRICAL CHARACTERISTICS

Table 5-3 summarizes the DC electrical characteristics of H8.

Table 5-3　　DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VIH	High-Level Input Voltage	0.7*VCC	-	VCC+0.3	V
VIL	Low-Level Input Voltage	-0.3	-	0.3*VCC	V
RPU	Input pull-up resistance	50	100	150	KΩ
RPD	Input pull-down resistance	50	100	150	KΩ
IIH	High-Level Input Current	-	-	10	uA
IIL	Low-Level Input Current	-	-	10	uA
VOH	High-Level Output Voltage	VCC-0.2	-	VCC	V
VOL	Low-Level Output Voltage	0	-	0.2	V
IOZ	Tri-State Output Leakage Current	-10	-	10	uA
CIN	Input Capacitance	-	-	5	pF
COUT	Output Capacitance	-	-	5	pF

5.4.　　OSCILLATOR ELECTRICAL CHARACTERISTICS

The 24.000MHz frequency is used to generate the main source clock for PLL and the main digital blocks，Table 5-4 lists the 24MHz crystal specifications.

Table 5-4　　24MHz Oscillator Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
$1/(t_{CPMAIN})$	Crystal Oscillator Frequency Range	-	24.000	-	MHz
t_{ST}	Startup Time	–	–		ms
	Frequency Tolerance at 25 °C	-40	–	+40	ppm
	Oscillation Mode	Fundamental			–
	Maximum change over temperature range	-50	–	+50	ppm
P_{ON}	Drive level	–	–	50	uW
C_L	Equivalent Load capacitance	–		–	pF
CL1,CL2	Internal Load capacitance(CL1=CL2)	–		–	pF
R_S	Series Resistance(ESR)	–		–	Ω
	Duty Cycle	30	50	70	%
C_M	Motional capacitance	–	–		pF
C_{SHUT}	Shunt capacitance	–	–		pF
R_{BIAS}	Internal bias resistor				MΩ

5.5.   POWER ON AND POWER OFF SEQUENCE

The external voltage regulator and other power-on devices must provide the processor with a specific sequence of power and resets to ensure proper operations.

Following Figure 5-1 and 5-2 illustrates the power on and off sequence:
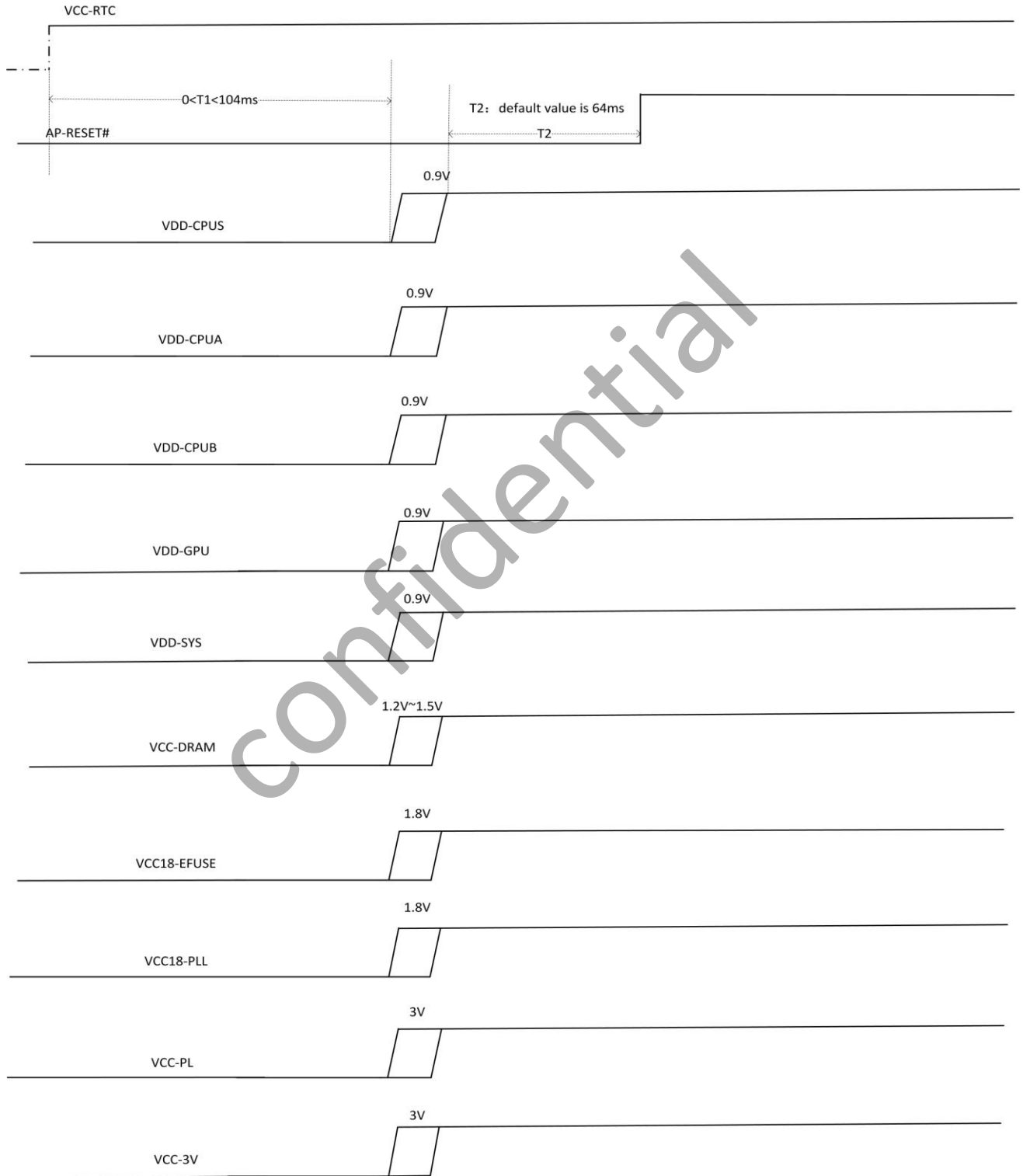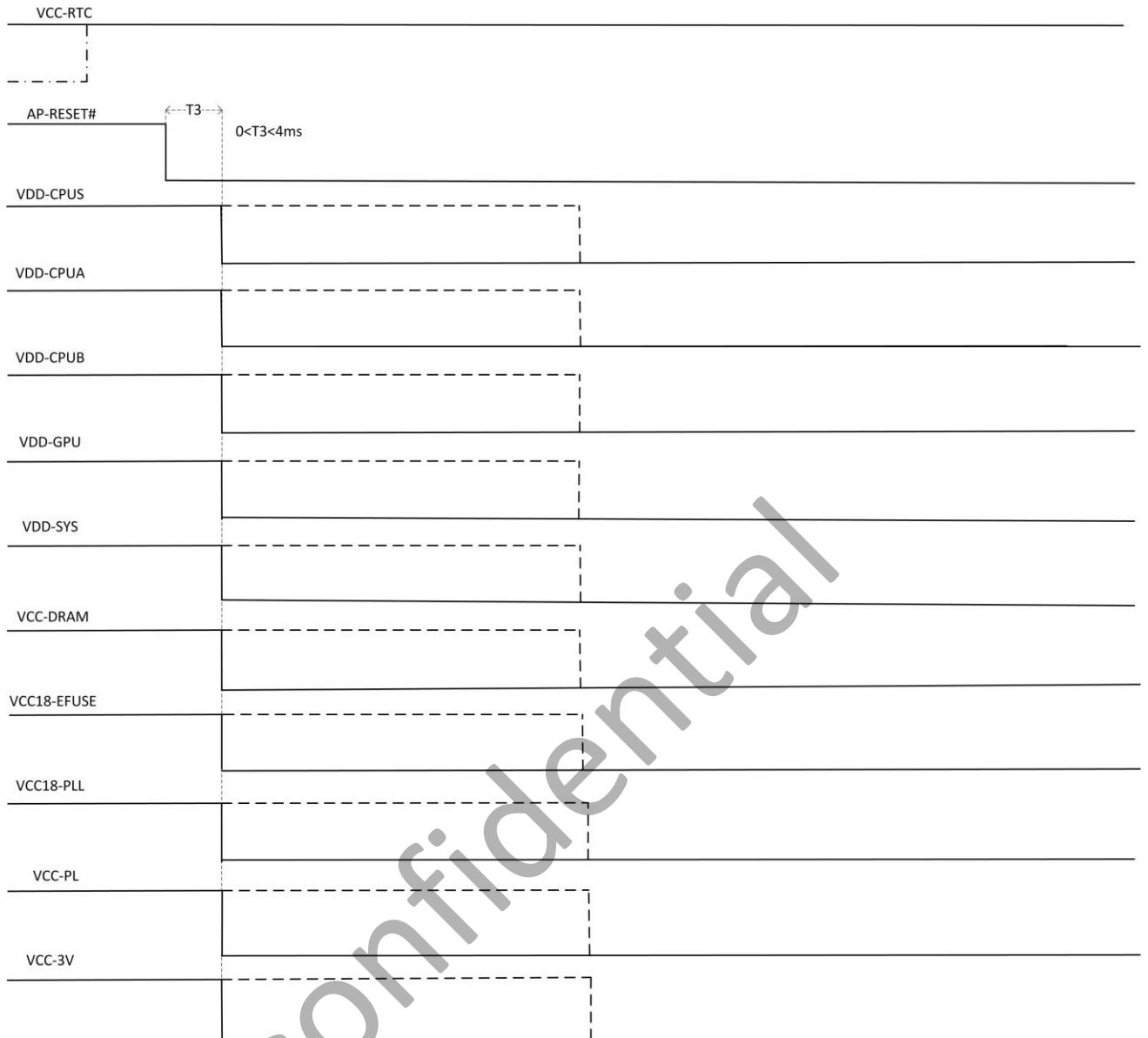

Figure 5-1.   Power On Timing
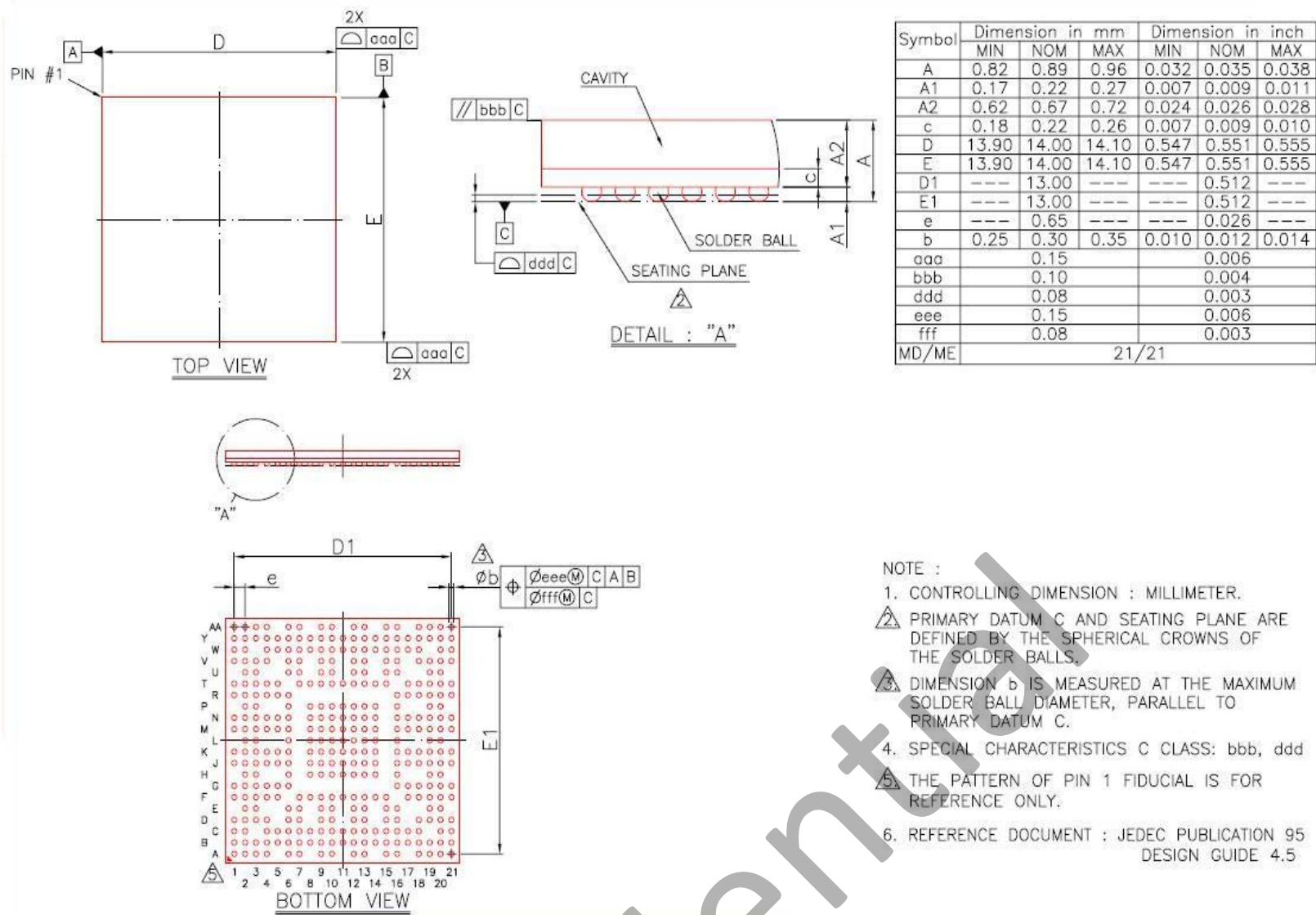
Figure 5-2.   Power Down Timing

6. PIN ASSIGNMENT

6.1.   PIN MAP

The following pin maps show the top views of the 345-pin FBGA package.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	
A	GND	SDQ20	SDQ23	SDQ24		SDQS3B	SDQ29		PB9	PB5		PE18	PE16		PD18	PD20		PD24	PD26	PD2	GND	A
B	SDQ22	SDQ21	SDQM3	SDQ25	SDQ27	SDQS3	SDQ31	SDQ30	PB7	PB3	PB2	PE17	PE15	PE8	PD19	PD21	PD22	PD25	PD27	PD3	PD6	B
C	SDQS2	SDQS2B		SDQ26	SRST	SDQ28	GND	PB8	PB4	PE19	GND	PE14	PE12	PE10	PE3	PD23	PD28	PD29		PD7	PD10	C
D	SDQ18	SDQ17	SDQ19	SRAS		SADBG	SDDBG1		PB10	PB0		PE13	PE7		PE4	PE2		PD4	PD5	PD11	PD12	D
E		SDQ16	SODT0			SDDBG0	VCC-DRAM		PB6	PB1		PE11	PE6		PE0	PE1			PD13	PD14		E
F	SWE	SCAS	SDQM2	SODT1	GND		VCC-DRAM	VDD18	VCC-IO	VDD-CPUB	VDD-CPUB	VCC18-LVDS	VCC-PD	VCC-PD	PE5		PE9	PD15	MDSI-DN3	MDSI-DP3	MDSI-DN2	F
G	SBA2	SBA0	SA8	SA9	SA13	GND										GND	GND	MDSI-CKN	MDSI-CKP	MDSI-DN1	MDSI-DP2	G
H		SA6	SA7		GND		GND		VDD-CPUB	VDD-CPUB	VDD-CPUB	GND	VCC18-MDSI	GND		GND			MDSI-DP1	MDSI-DN0		H
J	SCK	SCKB	SA5	SCKE0	SCKE1	VCC-DRAM		GND	VDD-CPUB	VDD-CPUB	VDD-CPUB	VDDFB-CPUB	GND	VDD-SYS		VDD-SYS	GND	HHPD	MDSI-DP0	HTX2P	HTX2N	J
K	SVREF	SCS0	SA4	SCS1	GND	VCC-DRAM		GND	GND	GND	GND	VDD09-HDMI	VCC18-HDMI		VDD-SYS	PG0	PG1	HTX0P	HTX1P	HTX1N		K
L		SDQ7	SA3			VCC-DRAM		GND	VDD-CPUA	VDD-CPUA	VDD-CPUA	VDD-CPUA	VCC-IO	VDD18		GND			PG2	HTX0N		L
M	SDQ4	SDQ5	SDQ6	SA2	SA1	VCC-DRAM		GND	VDD-CPUA	VDDFB-CPUA	VDD-CPUA	VDD-CPUA	VDD-CPUA	VDD-CPUA		PG3	PG4	PG5	PG6	HTXCP	HTXCN	M
N	SDQS0	SDQS0B	SDQ3	SA0	GND	VCC-DRAM		VDD-SPLL	GND	GND	GND	GND	VCC18-MCSI	GND		PG7	GND	PG8	PG9	PG10	PG11	N
P		SDQ2	SA10			VCC-DRAM		GND	VDD-GPU	VDD-GPU	VDD-GPU	GND	VDD09-USB	VCC12-HSIC		GND			PG12	MCSI-DN3		P
R	SDQ1	SDQ0	SDQM0	SA15	SA12	VCC-DRAM									VCC33-USB	VDD-CPUS	PG13		MCSI-DP3	MCSI-DP2	MCSI-DN2	R
T	SDQ15	SDQ14	SDQ13	SBA1	SZQ	VCC-IO	VDD18	PC14	PC8	VDD-GPU	VCC18-PLL	VCC18-ADC	GND-ADC	VCC-PL		VDD-CPUS	GND	MCSI-DN1	MCSI-CKP	MCSI-CKN		T
U		SDQ12	SA11			GND	PH8		PH0	PC9		X24MI	VCC18-EFUSE		UBOOT	PL7			MCSI-DN0	MCSI-DP1		U
V	SDQS1	SDQS1B	SDQ11	SA14		PH11	PH6		PC15	PC10		PC1	X24MO		PL4	PL3		PL11	MCSI-DP0	HSIC-STRB	HSIC-DATA	V
W	SDQ10	SDQ9		PF3	JTAGSEL	PH10	PH5	PH1	PC16	PC11	PC6	PC3	REXT	PL1	LRADC0	PL2	PL5	PL10		USB0-DM	USB0-DP	W
Y	SDQ8	SDQM1	PF5	PF1	PF0	PH9	PH4	PH2	PC17	PC12	PC7	PC4	PC0	TEST	RTC-VIO	NMI	PL6	PL9	USB0-VBUS	USB1-DP	USB0-ID	Y
AA	GND	PF6	PF4	PF2		PH7	PH3		PC18	PC13		PC5	PC2		PL0	RESET		PL8	PL12	USB1-DM	GND	AA
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	

6.2. PACKAGE DIMENSION

The following diagram shows the package dimension of the H8.

Symbol	Dimension in mm			Dimension in inch		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.82	0.89	0.96	0.032	0.035	0.038
A1	0.17	0.22	0.27	0.007	0.009	0.011
A2	0.62	0.67	0.72	0.024	0.026	0.028
c	0.18	0.22	0.26	0.007	0.009	0.010
D	13.90	14.00	14.10	0.547	0.551	0.555
E	13.90	14.00	14.10	0.547	0.551	0.555
D1	---	13.00	---	---	0.512	---
E1	---	13.00	---	---	0.512	---
e	---	0.65	---	---	0.026	---
b	0.25	0.30	0.35	0.010	0.012	0.014
aaa	0.15			0.006		
bbb	0.10			0.004		
ddd	0.08			0.003		
eee	0.15			0.006		
fff	0.08			0.003		
MD/ME	21/21					

NOTE :

1. CONTROLLING DIMENSION : MILLIMETER.

2. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. SPECIAL CHARACTERISTICS C CLASS: bbb, ddd

5. THE PATTERN OF PIN 1 FIDUCIAL IS FOR REFERENCE ONLY.

6. REFERENCE DOCUMENT : JEDEC PUBLICATION 95 DESIGN GUIDE 4.5

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